

Product / Process Change Notification



N° 2015-084-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of copper wire bond and additional wafer fab and wafer test location affecting TLE7240SL

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **19. September 2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: “**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► Products affected:	Sales Name	SP N°	OPN	Package
	TLE7240SL	SP000897440	TLE7240SLXUMA1	PG-SSOP-24

► Detailed Change Information:

Subject: Introduction of copper wire bond and additional wafer fab and wafer test location affecting TLE7240SL (Spider, SPT6).

Reason: Copper wire bonding is part of Infineon's continuous drive to deliver higher performance products. A copper wire enables superior electrical, thermal and reliability performance compared to Au, making it an excellent interconnect solution for automotive packaging.

Expansion of wafer production and wafer test capacity. Due to continuously raising demand for Infineon automotive products we have to implement the well-known front end (FE) location Kulim as an additional wafer fab and wafer test location.

Description:	<u>Old</u>	<u>New</u>
Wafer fab location	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Regensburg, Germany 	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Kulim, Malaysia or ■ Infineon Technologies AG, Regensburg, Germany
Wafer test location	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Villach, Germany 	<ul style="list-style-type: none"> ■ Infineon Technologies AG, Kulim, Malaysia or ■ Infineon Technologies AG, Villach, Germany
Wafer bond	<ul style="list-style-type: none"> ■ Gold 30 µm 	<ul style="list-style-type: none"> ■ Copper 30 µm or ■ Gold 30 µm
Glue	<ul style="list-style-type: none"> ■ EN4900 GC 	<ul style="list-style-type: none"> ■ A3230 or ■ EN4900 GC

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- ▶ **Product Identification:** Traceability assured via internal Bau-numbers.
No change in SP ordering number.

- ▶ **Impact of Change:** Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No impact on fit and form.

- ▶ **Attachments:** N.A.

- ▶ **Time Schedule:**
 - Final qualification report: available
 - First samples available: available
 - Intended start of delivery: 01-March-2017 or earlier after customer release

If you have any questions, please do not hesitate to contact your local Sales office.